

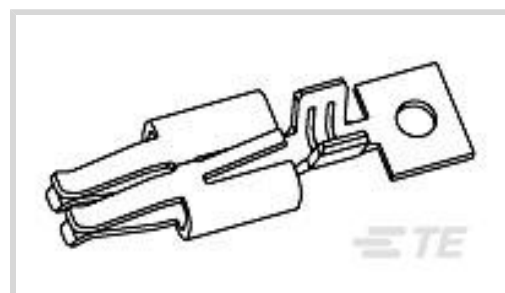
## LUMAWISE

TE Internal #: 2058302-1

Connector Contact, Socket, Wire-to-Board, 22 – 18 AWG Wire Size,  
642 – 1624 CMA Wire Size, .325 – .823 mm<sup>2</sup> Wire Size, Tin, Strip,  
Wire & Cable, 6 A

[View on TE.com >](#)

Connectors > PCB Connectors > Wire-to-Board Connectors > Wire-to-Board Connector Contacts

Contact Type: **Socket**Connector System: **Wire-to-Board**Wire Size: .325 – .823 mm<sup>2</sup>

## Features

### Product Type Features

Connector System	Wire-to-Board
Connector & Contact Terminates To	Wire & Cable

### Configuration Features

Compatible With Wire & Cable Type	Discrete Wire
-----------------------------------	---------------

### Contact Features

Mating Tab Width	3 mm[.118 in]
Mating Tab Thickness	.4 mm[.016 in]
Contact Mating Area Plating Material Finish	Matte
Contact Length	11.9 mm[.468 in]
Contact Type	Socket
Contact Mating Area Plating Material	Tin
Contact Current Rating (Max)	6 A

### Termination Features

Termination Method to Wire & Cable	Crimp
------------------------------------	-------

### Dimensions

Wire Size	.325 – .823 mm <sup>2</sup>
-----------	-----------------------------

### Usage Conditions

Operating Temperature Range	-40 – 105 °C[-40 – 221 °F]
-----------------------------	----------------------------

### Operation/Application



Circuit Application

Signal

### Industry Standards

Glow Wire Rating

Standard Part - Not Glow Wire

### Packaging Features

Packaging Method

Strip

## Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU

Compliant

EU ELV Directive 2000/53/EC

Compliant

China RoHS 2 Directive MIIT Order No 32, 2016

No Restricted Materials Above Threshold

EU REACH Regulation (EC) No. 1907/2006

Current ECHA Candidate List: JAN 2022 (223)  
 Candidate List Declared Against: JAN 2022 (223)  
 Does not contain REACH SVHC

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability

Not applicable for solder process capability

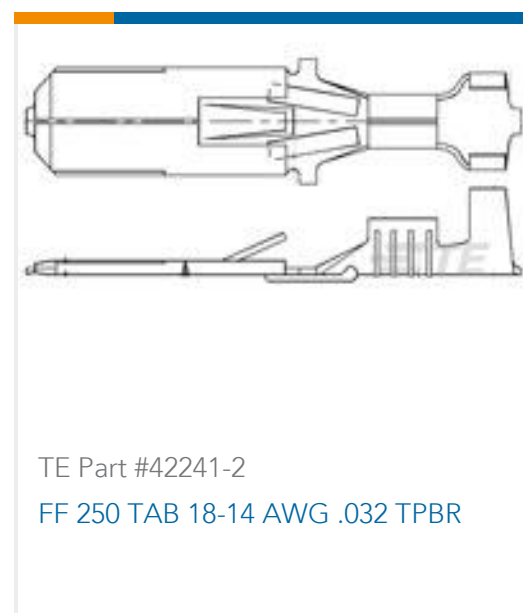
#### Product Compliance Disclaimer

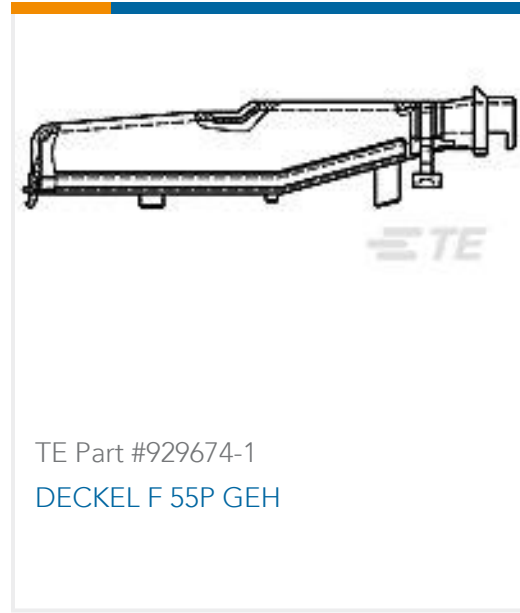
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

## Compatible Parts



### Customers Also Bought





## Documents

### Product Drawings

[Socket Contact](#)

English

### Datasheets & Catalog Pages

[HERMAPHRODITIC\\_WIRE-TO-BOARD\\_AND\\_BOARD-TO-BOARD](#)

[HERMAPHRODITIC\\_WIRE-TO-BOARD\\_AND\\_BOARD-TO-BOARD](#)

English

### Product Specifications

[Application Specification](#)

English